

FORM PTO-1595

(Rev. 08/05)

04-11-2007



103393623

U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office

Docket No.: 075905-0034 103393623		
To the Director of the U. S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.		
1. Name of Conveying Party(ies) 4,5.07	2. Name and address of receiving party(ies)	
Takehiro HIRAI	Name: HITACHI HIGH-TECHNOLOGIES	
	CORPORATION	
Additional name(s) of conveying party(ies) attached? Yes No		
3. Nature of Conveyance/Execution Date(s)	Address: 1-24-14, Nishi Shimbashi,	
Execution Date(s): February 22, 2007	Minato-ku,	
Assignment	Tokyo, 105-8717 JAPAN	
Security Agreement Change of Name		
Joint Research Agreement		
Government Interest Assignment		
Executive Order 9424, Confrmatory License	Additional name (a) & address (a) to 10 Tay Tay	
Other	Additional name(s) & address(es) attached? Yes No	
4. Application or patent number(s):	This document is being filed together with a new application.	
A. Patent Application No(s).	B. Patent No(s).	
11/699,063, filed on January 29, 2007		
Additional numbers attached? Yes No		
5. Name and address to whom correspondence concerning document should be mailed:	6. Total number of applications and patents 1 involved:	
Name: MCDERMOTT WILL & EMERY LLP	7. Total fee (37 CFR 1.21(h) & 3.41) \$40.00	
Internal Address:	Authorized to be charged by credit card	
internal Address.		
Street Address: 600 13th Street, N.W.	Authorized to be charged to deposit account Enclosed	
Street Address. Gov 13th Street, IV. W.		
City Washington State D.C. 71: 20005 2007	None required (government interest not affecting title)nt	
City: Washington State: D. C. Zip: 20005-3096	0 P	
Phone Number: 202.756.8000	8. Payment Information:	
Fax Number: 202.756.8087		
Email Address:	a. Credit Card Last 4 Numbers Expiration Date Deposit Account Number 500417	
	Authorized User Name	
	Authorized User Name	
9. Signature.		
Keith E. George, 34,111 April 42007		
Name and Registration No. of Person Signing Signature Dake		
	ng cover sheet, attachments and documents:	
OMB No. 0651-0027 (exp. 6/30/2008)	2	

PATENT REEL: 019168 FRAME: 0818

ASSIGNMENT (譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi High-Technologies Corporation, a corporation organized under the laws of Japan,

located at 1-24-14, Nishi Shimbashi, Minato-ku, Tokyo, 105-8717 Japan

receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi High-Technologies Corporation, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

REPORT FORMAT SETTING METHOD AND APPARATUS. AND DEFECT REVIEW SYSTEM

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said Hitachi High-Technologies Corporation,

INVENTOR(S)

its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-inpart, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi High-Technologies Corporation,

Signed on the date(s) indicated aside our signatures:

RECORDED: 04/05/2007

	(発明者フルネームサイン)	(署名日)
1)	Tekehiro Hirai	2/22/2007
2)		
3)		

PATENT REEL: 019168 FRAME: 0819

Date Signed